4a). It is preferred that the surface 81 be substantially planar and that this surface be rough or sticky. The article 80 is subsequently pushed into contact with the insulating layer 36 of the precursor circuit element 20p toward the bumps 30 (in the direction of the arrow 82), such that only the insulating layer 36, along the apexes 32 of the bumps 30 (preferably along an arc proximate the apex 32) beyond plane A, contacts the article surface 81 (FIG. 4b).

Amend the last paragraph beginning on page 11 and continuing on to page 12 as follows:

As shown in FIG. 4c, upon removal (separation) of the article 80 from the precursor circuit element 20p (now the circuit element 20'')(in the direction of the arrow 84), the insulating layer portions 36', formerly on the precursor circuit element 20p, are now on the article surface 81. With the insulating layer portions 36' removed, the resultant circuit element 20'' has a now-exposed bump surface 30a proximate the bump apexes 32. This exposed bump surface 30a is sufficient to promote an electrical connection between this circuit element 20" and another circuit element (e.g., circuit element 21), while substantial amounts of the insulating layer 36 remain on the substrate 22 and bump 30 to facilitate the mechanical connection between the above circuit elements. Preferably a sufficient amount of the remaining insulating layer 36 remains intact, having been unaffected by this removal step. Upon completion of the removal step, the circuit element 20'' is ready for further processing, in accordance with the methods as detailed below (as described below for circuit element 20).

A version marked up to show changes made to the specification relative to the previous version of the specification is attached.